

## **A MINIATURISED SURFACE MOUNT OPTOELECTRONIC COMPONENT**

### **ABSTRACT**

5 The invention relates to a miniaturised surface mount optoelectronic component. An electrically conductive material (1) preferably metal frame is used to serve as the base for the assembly. Optionally a cavity (2) may be formed within this electrically conductive base material to serve as a reflector cup. An optoelectronic chip (3) is mounted within this cavity. The whole base material is then encapsulated with a hard  
10 transparent or translucent resin material (4) so that optical radiation may be transmitted or received via this medium. Electrical connection(s) between the chip and the base material is provided by a metallic wire or wires (6).

The Most Illustrative Drawing: FIG. A